

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Hui Ou-Yang et al.

SERIAL NO.: 10/080,882

FILED: February 20, 2002

FOR: HIGH DENSITY PLASMA POST-ETCH

TREATMENT FOR A DIELECTRIC

ETCH PROCESS

GROUP ART UNIT: 1763

EXAMINER: A. W. Olsen

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Attorney Docket No.: AM-3467.C1

Date: February 6, 2004

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AMENDMENT "B" UNDER 37 CFR § 1.111

Hon. Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

Sir:

This Amendment "B" is in response to the Office Action mailed October 7, 2003, having a shortened statutory period for response of January 7, 2004. A Petition for a One Month Extension of Time to respond to the Office Action accompanies this Amendment "B", to extend the time for response through February 9, 2004.

Claims 1 - 18 are pending in the application.

CERTIFICATE OF MAILING UNDER 37 CFR § 1.10

I hereby certify that this paper is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as U.S. EXPRESS MAIL NO. ER534274121US in an envelope addressed to: Mail Stop Amendment (With Fee), Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: February 9, 2004

Shirley L. Church, Reg. No. 31,858